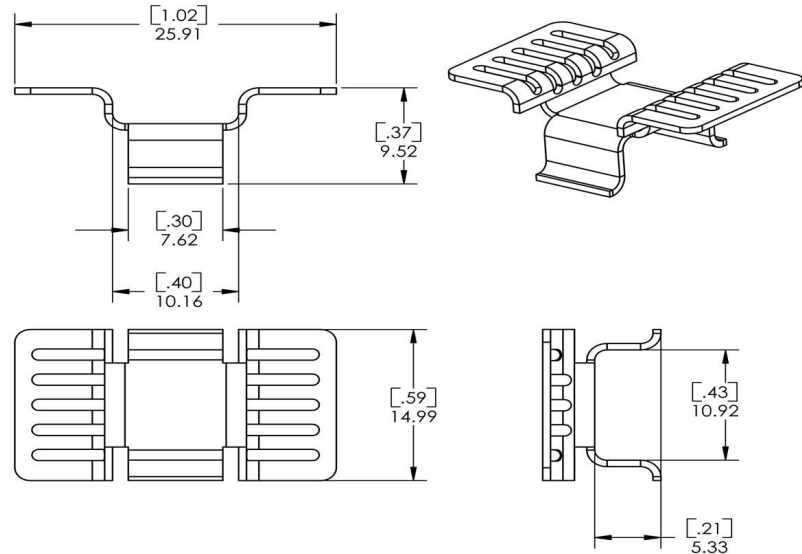
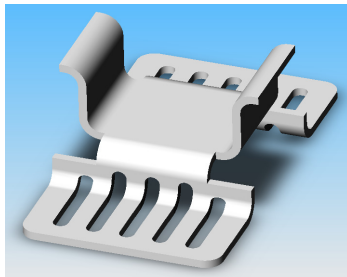


Board Level Heat Sinks



ThermaFlo®

P/N: 833900T00000 & 8339TRT00000



PRODUCT SPECIFICATIONS

- Devices: D PAK, TO-263, SO-10, MO-184
- Size: 25.9 x 15.0 x 9.5 mm
- Material: Copper, 0.6 mm Thick
- Type: Stamped
- PCB Mounting: Surface Mount Technology
- Finish: Tin Plate
- Package: Bulk or Tape & Reel

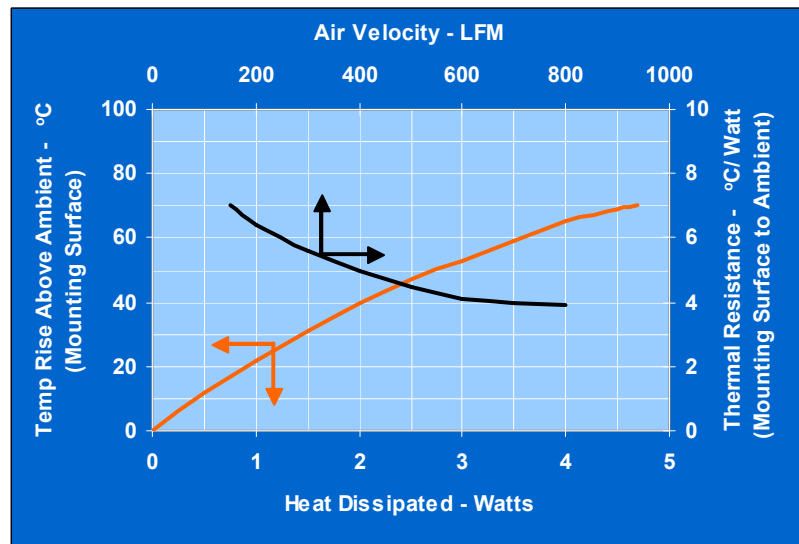
FEATURES & BENEFITS

- No Hardware Device Attachment
- Direct SMT Contact to PCB
- Solderable Legs
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



D PAK, TO-263, SO-10, MO-184

Part Number	Packaging	Notes
833900T00000	Bulk	
8339TRT00000	Tape & Reel	Contact Factory for Tape and Reel Specs

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